

IN THE SPECIFICATION

Please amend Paragraph [0013] as follows:

-- [0013] Figures 1, 2, and 3 illustrate a microelectronic assembly 10, according to one embodiment of the invention, including a package substrate subassembly 12, a die subassembly 14, and wirebonding wires 16A, 16Bi, and 16Bii. --

Please amend Paragraph [0028] as follows:

-- [0028] Figures 6 and 7 illustrate a microelectronic assembly 210 according to a further embodiment of the invention. The microelectronic assembly 210 includes a package substrate subassembly 212, a die subassembly 214, two redistribution conductors formed by elongate redistribution pads 270A and 270B, and redistribution wirebonding wires 272A and 272B. --

Please amend Paragraph [0030] as follows:

-- [0030] The die subassembly 214 includes a die 225 and plurality of contacts 226A and 226B on the die 224. The die 225 includes a die substrate and an integrated circuit formed on the die substrate. --